

FEATURES

- Dual Device Module
- Electrically Isolated Package
- Pressure Contact Construction
- International Standard Footprint
- Alumina (non-toxic) Isolation Medium

APPLICATIONS

- Motor Control
- Controlled Rectifier Bridges
- Heater Control
- AC Phase Control

VOLTAGE RATINGS

Type Number	Repetitive Peak Voltages V_{DRM} V_{RRM}	Conditions
MP03/300 - 16	1600	$T_{(vj)} = 125^{\circ}\text{C}$ $I_{DRM} = I_{RRM} = 30\text{mA}$ $V_{DSM} \text{ \& } V_{RSM} =$ $V_{DRM} \text{ \& } V_{RRM} + 100\text{V}$ respectively
MP03/300 - 14	1400	
MP03/300 - 12	1200	
MP03/300 - 10	1000	

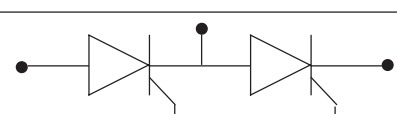
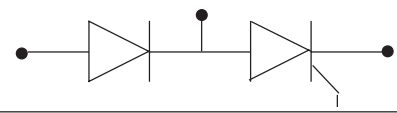
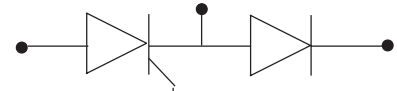
Lower voltage grades available.

For full description of part number see "Ordering instructions" on page 3.

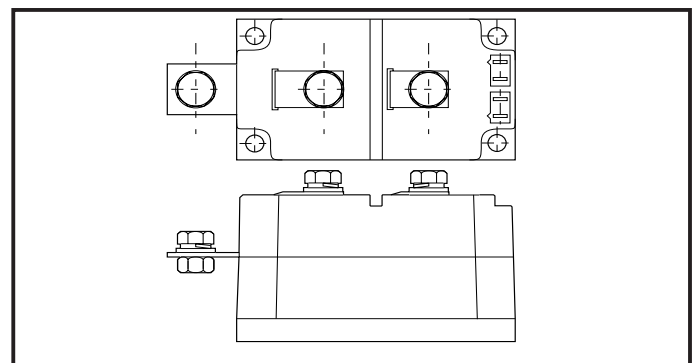
KEY PARAMETERS

V_{DRM}	1600V
I_{TSM}	10600A
$I_{T(AV)}$ (per arm)	312A
V_{isol}	2500V

CIRCUIT OPTIONS

Code	Circuit
HBT	
HBP	
HBN	

PACKAGE OUTLINE



Module type code: MP03.

See Package Details for further information

CURRENT RATINGS - PER ARM

Symbol	Parameter	Conditions	Max.	Units	
$I_{T(AV)}$	Mean on-state current	Halfwave, resistive load	$T_{case} = 75^{\circ}\text{C}$	312	A
			$T_{case} = 85^{\circ}\text{C}$	265	A
			$T_{heatsink} = 75^{\circ}\text{C}$	216	A
			$T_{heatsink} = 85^{\circ}\text{C}$	181	A
$I_{T(RMS)}$	RMS value	$T_{case} = 75^{\circ}\text{C}$	490	A	

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SURGE RATINGS - PER ARM

Symbol	Parameter	Conditions		Max.	Units
I_{FSM}	Surge (non-repetitive) on-state current	10ms half sine; $T_j = 125^\circ\text{C}$	$V_R = 0$	10.6	kA
			$V_R = 50\% V_{RRM}$	8.5	kA
I^2t	I^2t for fusing	10ms half sine; $T_j = 125^\circ\text{C}$	$V_R = 0$	0.56×10^6	A^2s
			$V_R = 50\% V_{RRM}$	0.36×10^6	A^2s

THERMAL & MECHANICAL RATINGS

Symbol	Parameter	Conditions	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case per Thyristor or Diode	dc	0.11	$^\circ\text{C}/\text{W}$
		halfwave	0.12	$^\circ\text{C}/\text{W}$
		3 phase	0.13	$^\circ\text{C}/\text{W}$
$R_{th(c-hs)}$	Thermal resistance - case to heatsink per thyristor or diode	Mounting torque = 5Nm with mounting compound	0.05	$^\circ\text{C}/\text{W}$
T_{vj}	Virtual junction temperature	Off-state (Blocking)	125	$^\circ\text{C}$
T_{stg}	Storage temperature range		-40 to 125	$^\circ\text{C}$
V_{isol}	Isolation voltage	Commoned terminals to base plate AC RMS, 1min, 50Hz	2.5	kV

DYNAMIC CHARACTERISTICS- THYRISTOR

Symbol	Parameter	Conditions	Max.	Units
V_{TM}	On-state voltage	At 1000A, $T_{case} = 25^\circ\text{C}$ - See Note 1	1.50	V
I_{RRM}/I_{DRM}	Peak reverse and off-state current	At V_{RRM}/V_{DRM} , $T_j = 125^\circ\text{C}$	30	mA
dV/dt	Linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125^\circ\text{C}$	200*	$\text{V}/\mu\text{s}$
dI/dt	Rate of rise of on-state current	From 67% V_{DRM} to 600A Gate source 10V, 5 Ω Rise time 0.5 μs , $T_j = 125^\circ\text{C}$	100	$\text{A}/\mu\text{s}$
$V_{T(TO)}$	Threshold voltage	At $T_{vj} = 125^\circ\text{C}$ - See Note 1	0.8	V
r_T	On-state slope resistance	At $T_{vj} = 125^\circ\text{C}$ - See Note 1	0.7	m Ω

* Higher dV/dt values available, contact factory for particular requirements.

Note 1: The data given in this datasheet with regard to forward voltage drop is for calculation of the power dissipation in the semiconductor elements only. Forward voltage drops measured at the power terminals of the module will be in excess of these figures due to the impedance of the busbar from the terminal to the semiconductor.

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Conditions	Typ.	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	-	3.0	V
I_{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	-	150	mA
V_{GD}	Gate non-trigger voltage	At $V_{DRM}, T_{case} = 25^{\circ}C$	-	0.25	V
V_{FGM}	Peak forward gate voltage	Anode positive with respect to cathode	-	30	V
V_{FGN}	Peak forward gate voltage	Anode negative with respect to cathode	-	0.25	V
V_{RGM}	Peak reverse gate voltage		-	5.0	V
I_{FGM}	Peak forward gate current	Anode positive with respect to cathode	-	10	A
P_{GM}	Peak gate power	$t_p = 25\mu s$	-	100	W
$P_{G(AV)}$	Mean gate power		-	5	W

ORDERING INSTRUCTIONS

Part number is made up of as follows:

MP03 HBT 300 -12

MP = Pressure contact module
 03 = Outline type
 HBT = Circuit configuration code (see "circuit options" - front page)
 300 = Nominal average current rating at $T_{case} = 75^{\circ}C$
 12 = $V_{RRM}/100$

Examples:

MP03 HBP300 - 16
 MP03 HBN300 - 10
 MP03 HBT300 - 14

NOTE: Diode ratings and characteristics are comparable with the SCR in types HBP or HBN
 Types HBP or HBN can also be supplied with diode polarity reversed, to special order.

MOUNTING RECOMMENDATIONS

■ Adequate heatsinking is required to maintain the base temperature at $75^{\circ}C$ if full rated current is to be achieved. Power dissipation may be calculated by use of $V_{T(TO)}$ and r_T information in accordance with standard formulae. We can provide assistance with calculations or choice of heatsink if required.

■ The heatsink surface must be smooth and flat; a surface finish of N6 ($32\mu in$) and a flatness within $0.05mm$ ($0.002"$) are recommended.

■ Immediately prior to mounting, the heatsink surface should be lightly scrubbed with fine emery or Scotch Brite or a mild chemical etchant and then cleaned with a solvent to remove oxide build up and foreign material. Care should be taken to ensure no foreign particles remain.

■ An even coating of thermal compound (eg. Unial) should be applied to both the heatsink and module mounting surfaces. This should ideally be $0.05mm$ ($0.002"$) per surface to ensure optimum thermal performance.

■ After application of thermal compound, place the module squarely over the mounting holes, (or 'T' slots) in the heatsink. Using a torque wrench, slowly tighten the recommended fixing bolts at each end, rotating each in turn no more than $1/4$ of a revolution at a time. Continue until the required torque of $5Nm$ ($44lb.ins$) is reached at both ends.

■ It is not acceptable to fully tighten one fixing bolt before starting to tighten the others. Such action may DAMAGE the module.

CURVES

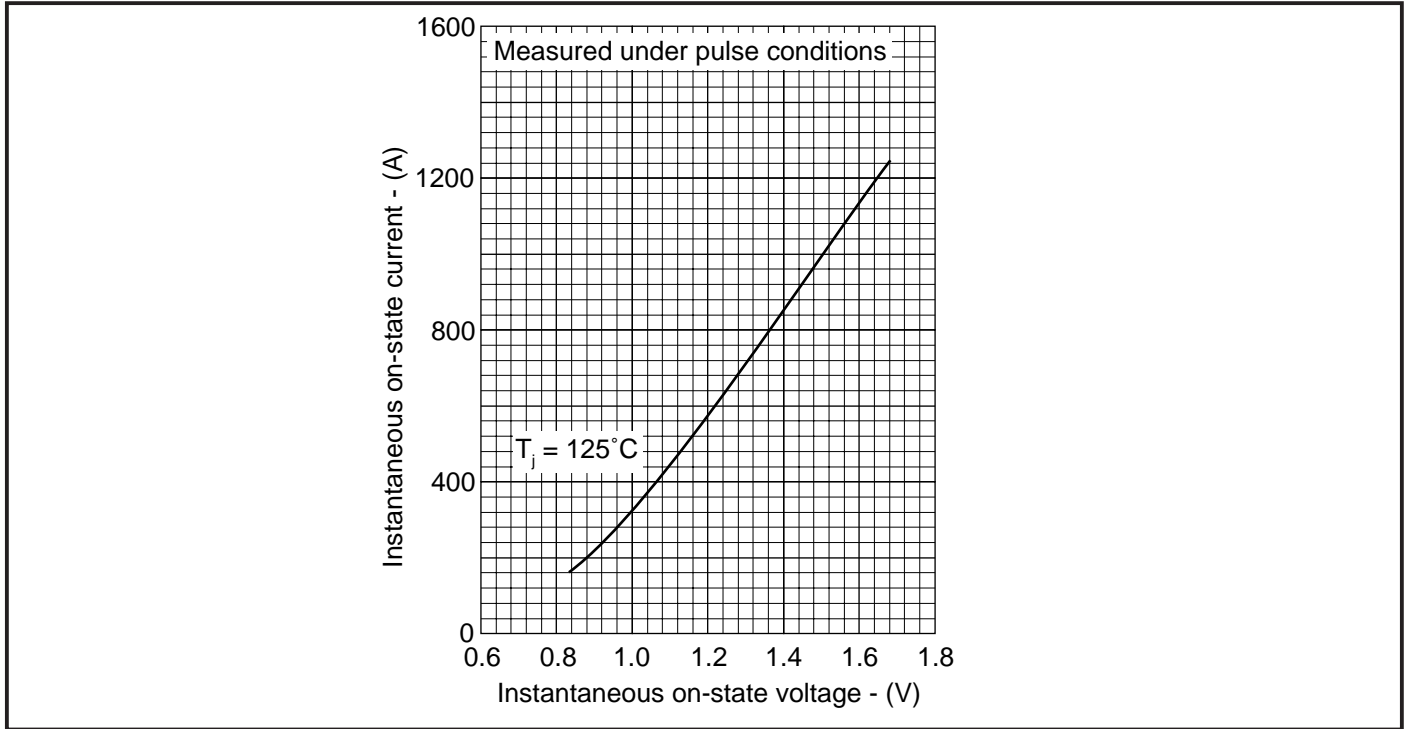


Fig. 1 Maximum (limit) on-state characteristics (thyristor or diode) - See Note 1

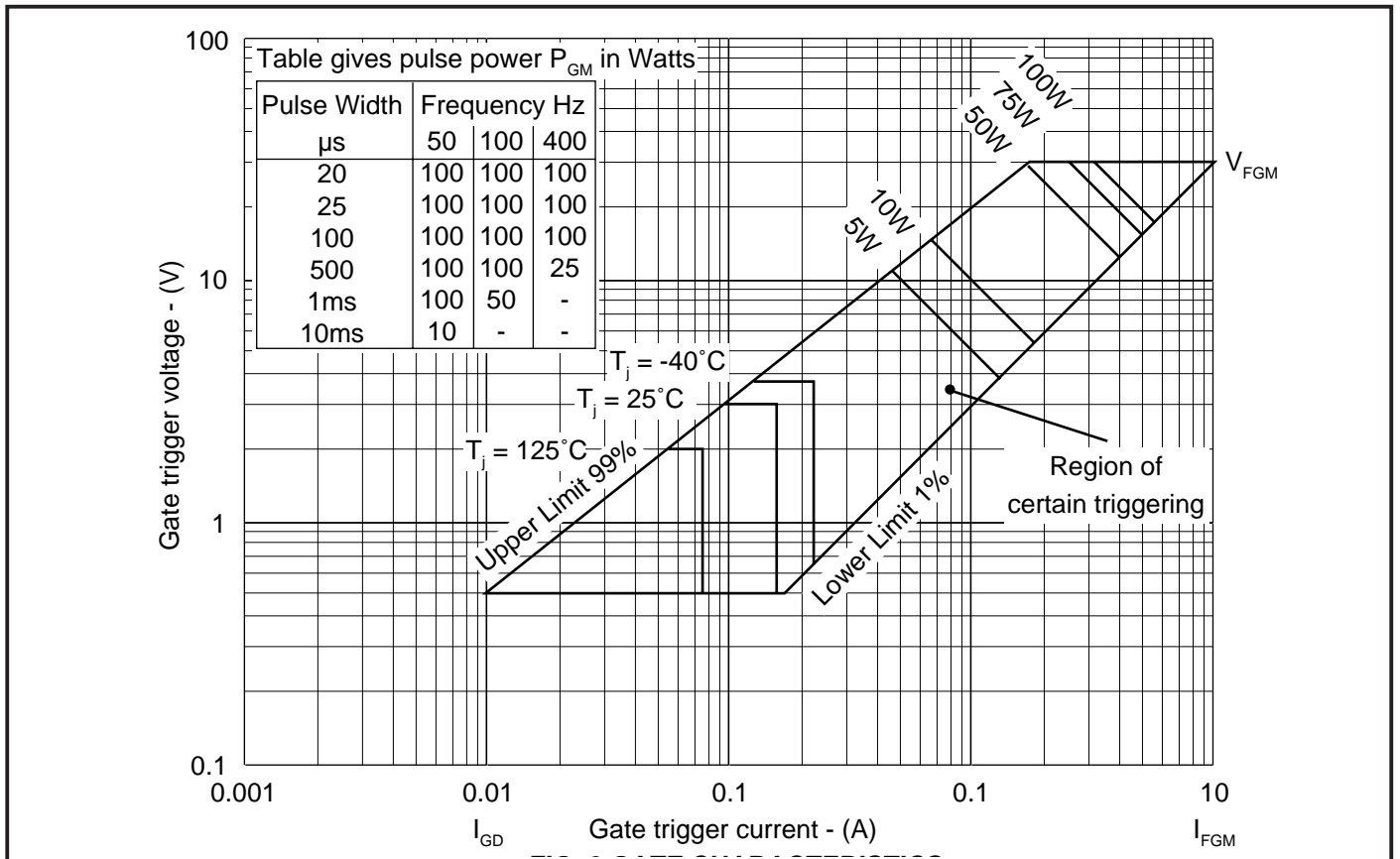


Fig. 2 Gate trigger characteristics

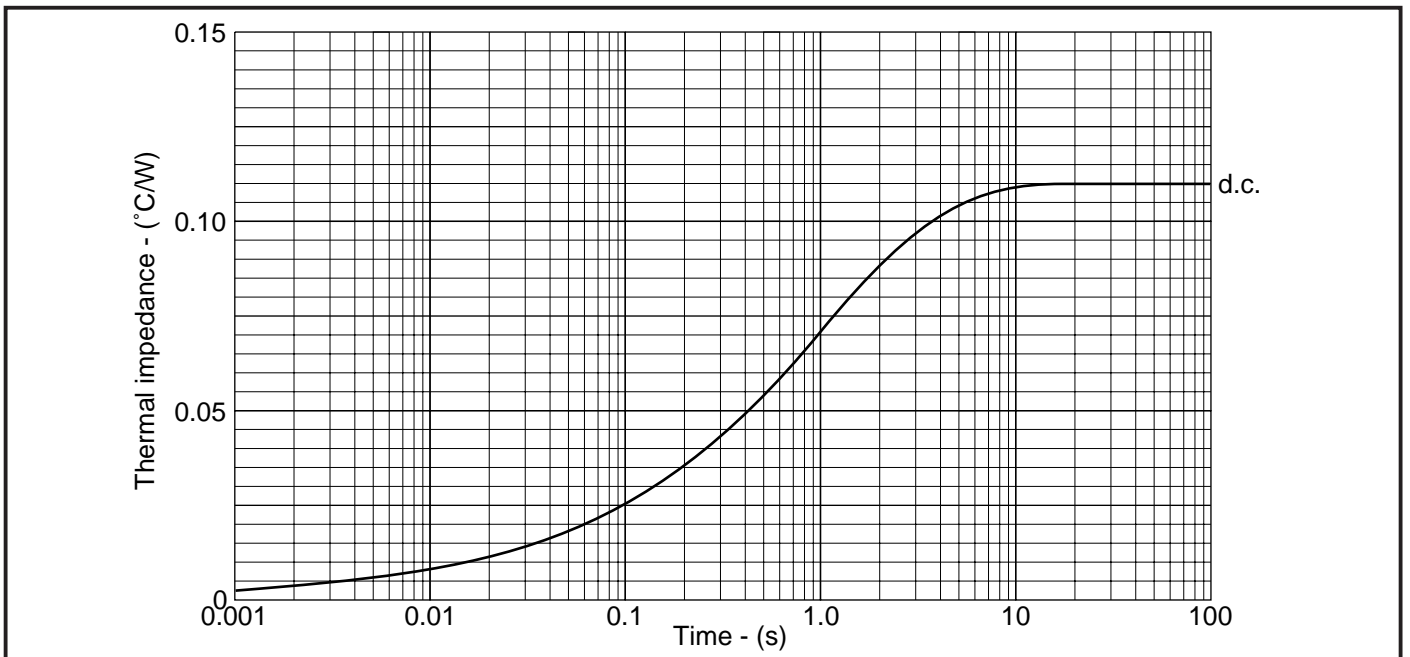


Fig. 3 Transient thermal impedance (DC) - (Thyristor or diode)

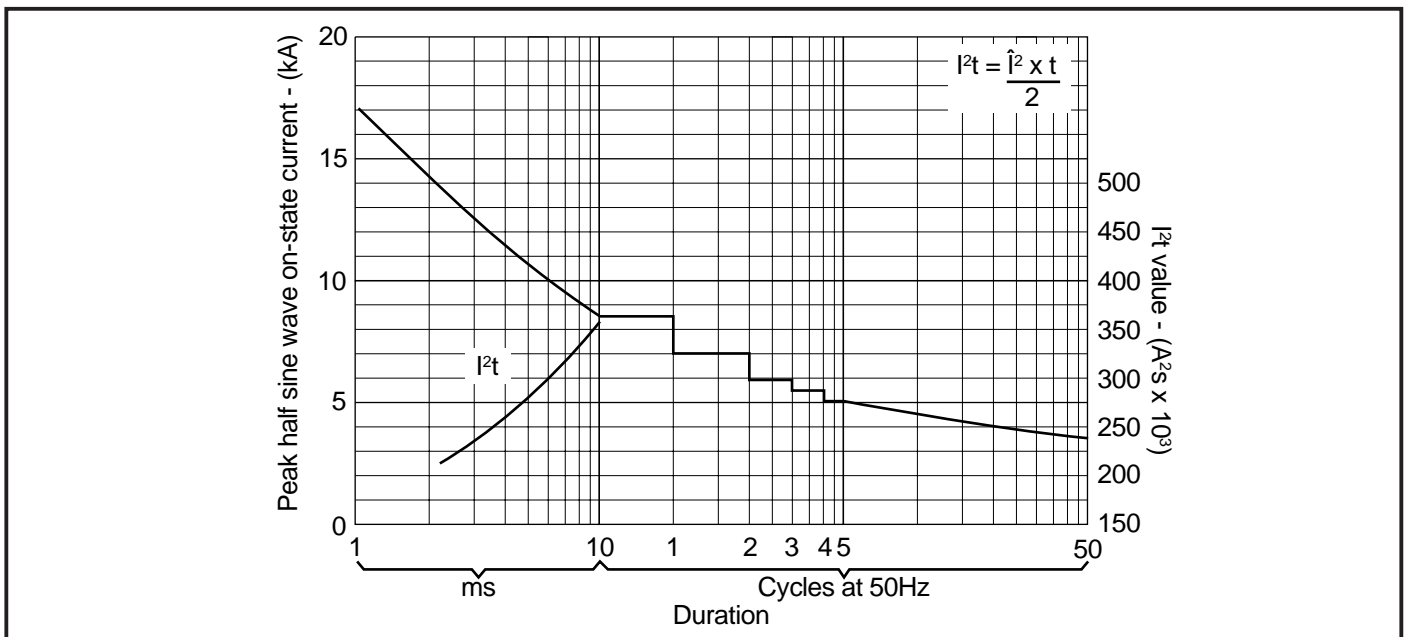


Fig. 4 Surge (non-repetitive) on-state current vs time (with 50% V_{RRM} , $T_{case} = 125^\circ C$) (Thyristor or diode)

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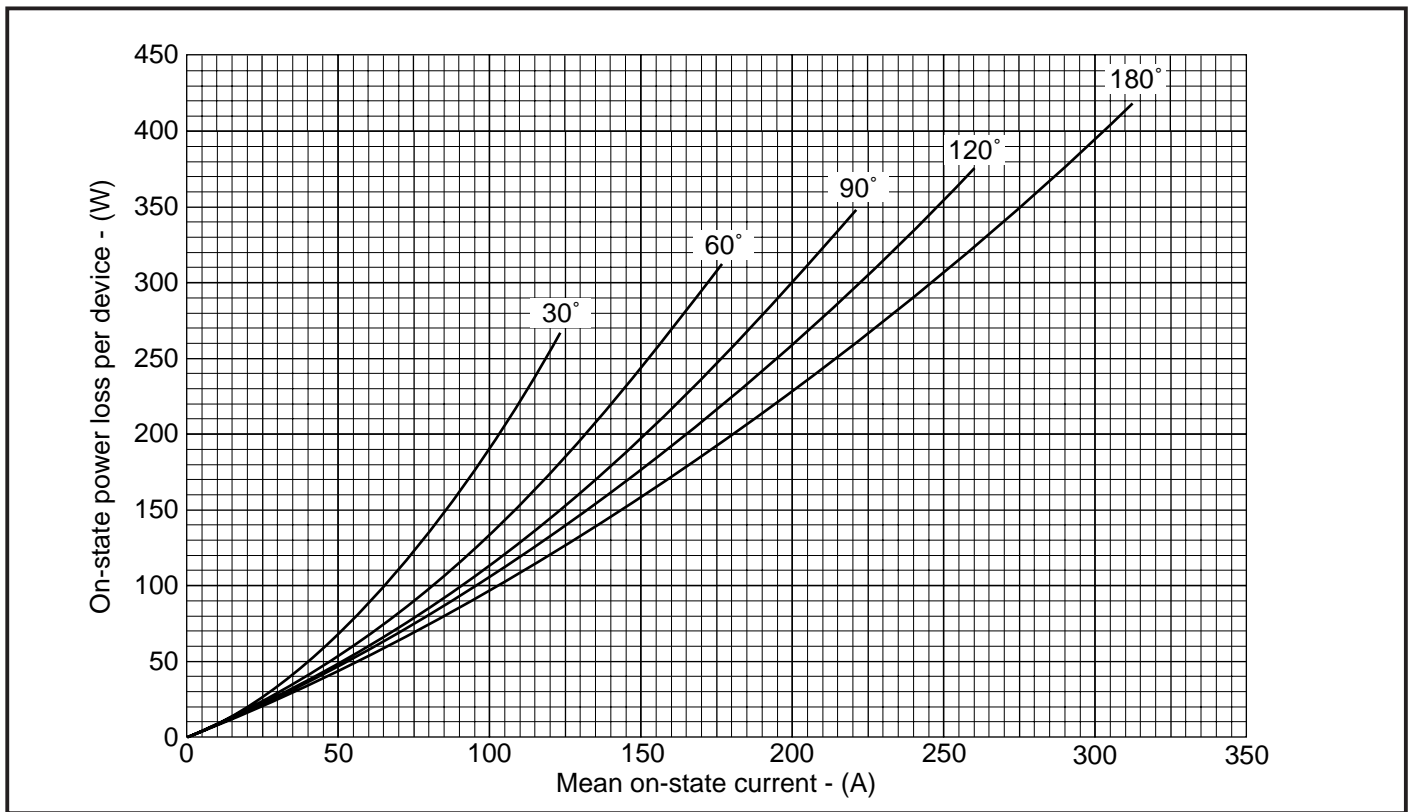


Fig. 5 On-state power loss per arm vs forward current at various conduction angles, sine wave, 50/60Hz

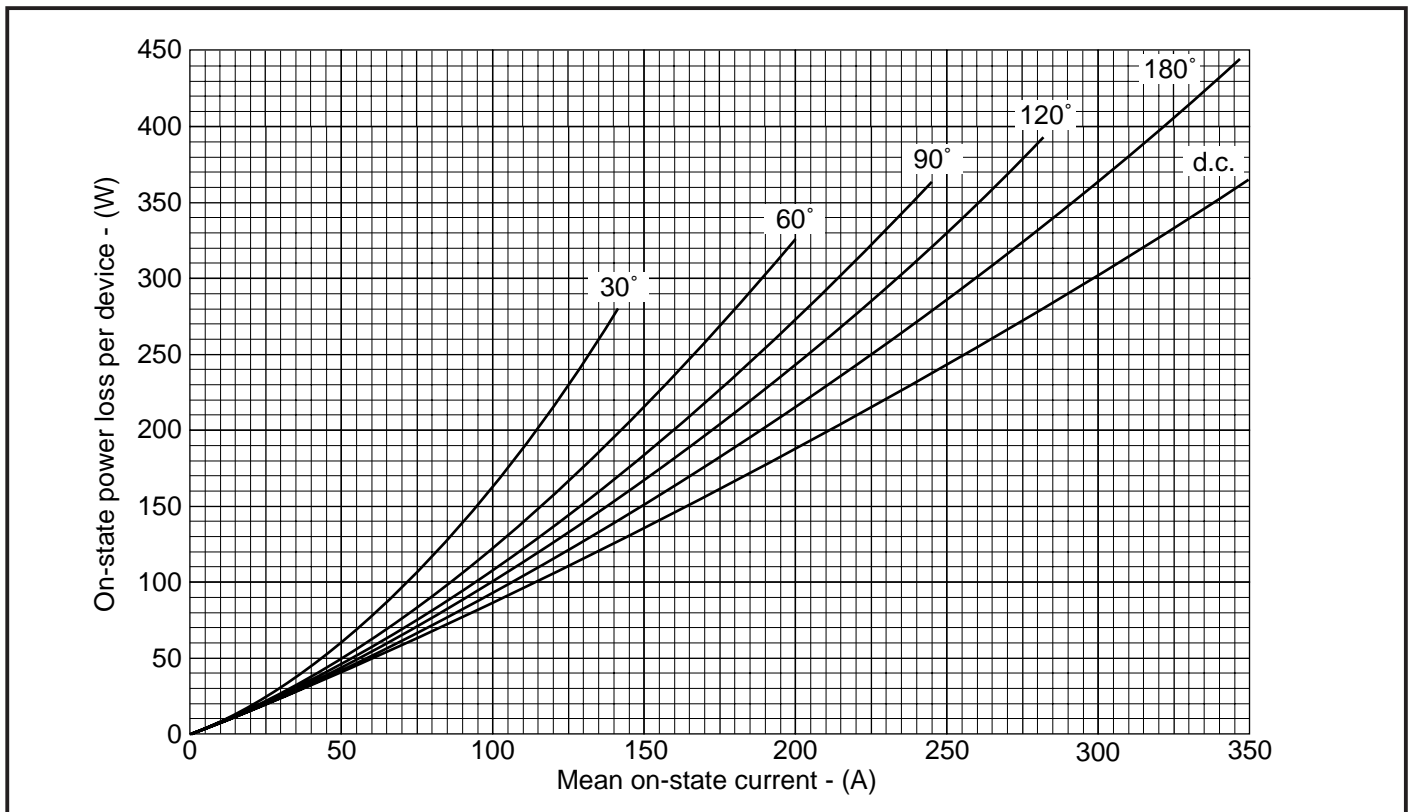


Fig. 6 On-state power loss per arm vs forward current at various conduction angles, square wave, 50/60Hz

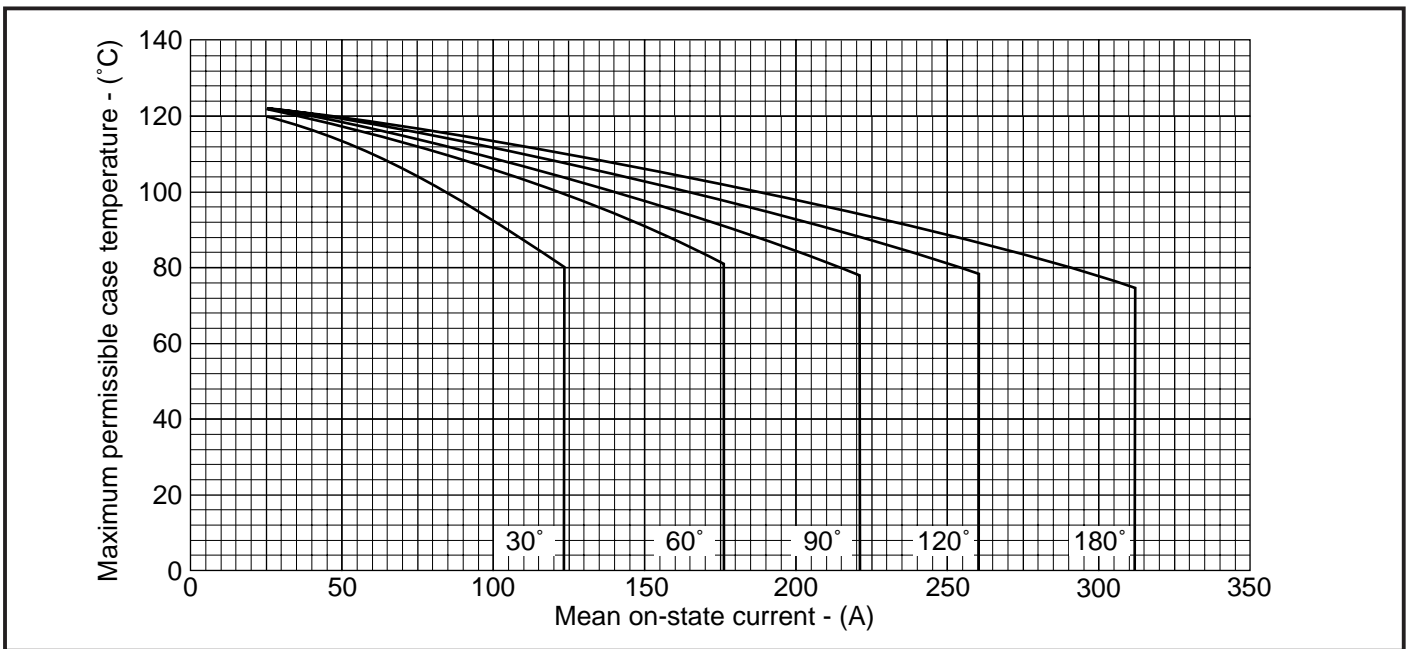


Fig. 7 Maximum permissible case temperature vs forward current per arm at various conduction angles, sine wave, 50/60Hz

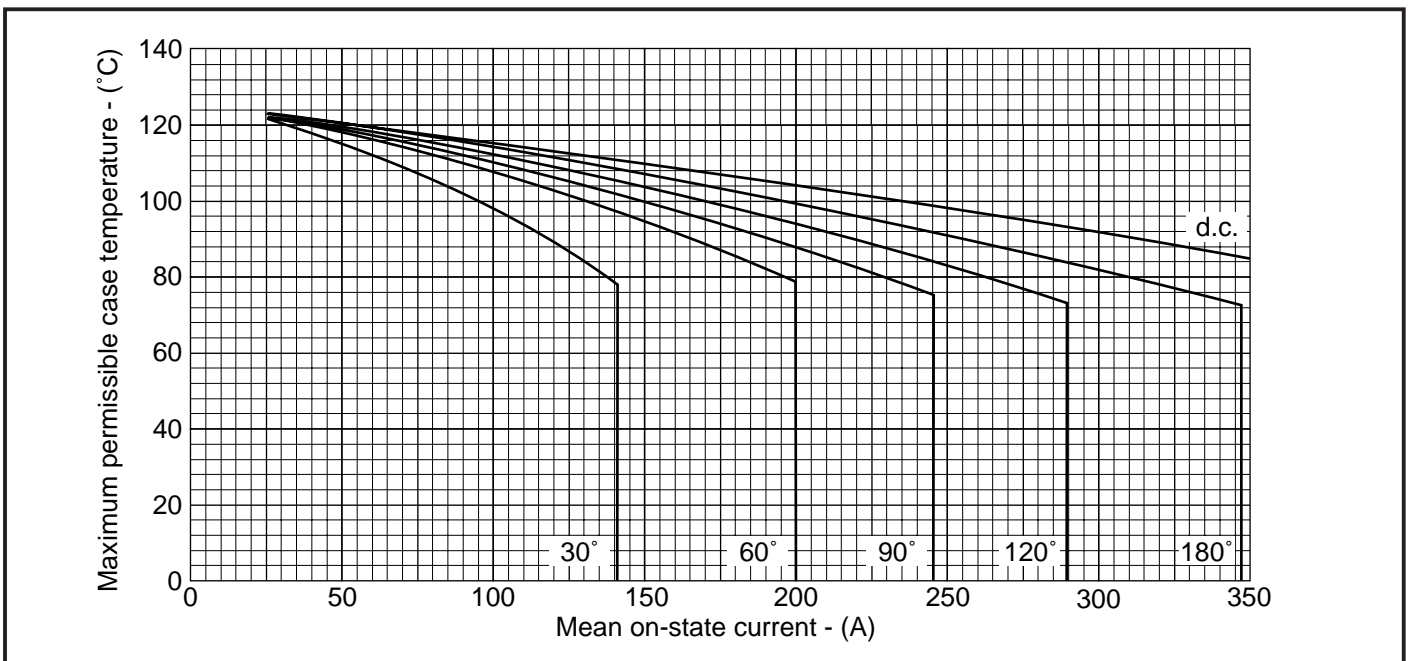


Fig. 8 Maximum permissible case temperature vs forward current per arm at various conduction angles, square wave, 50/60Hz

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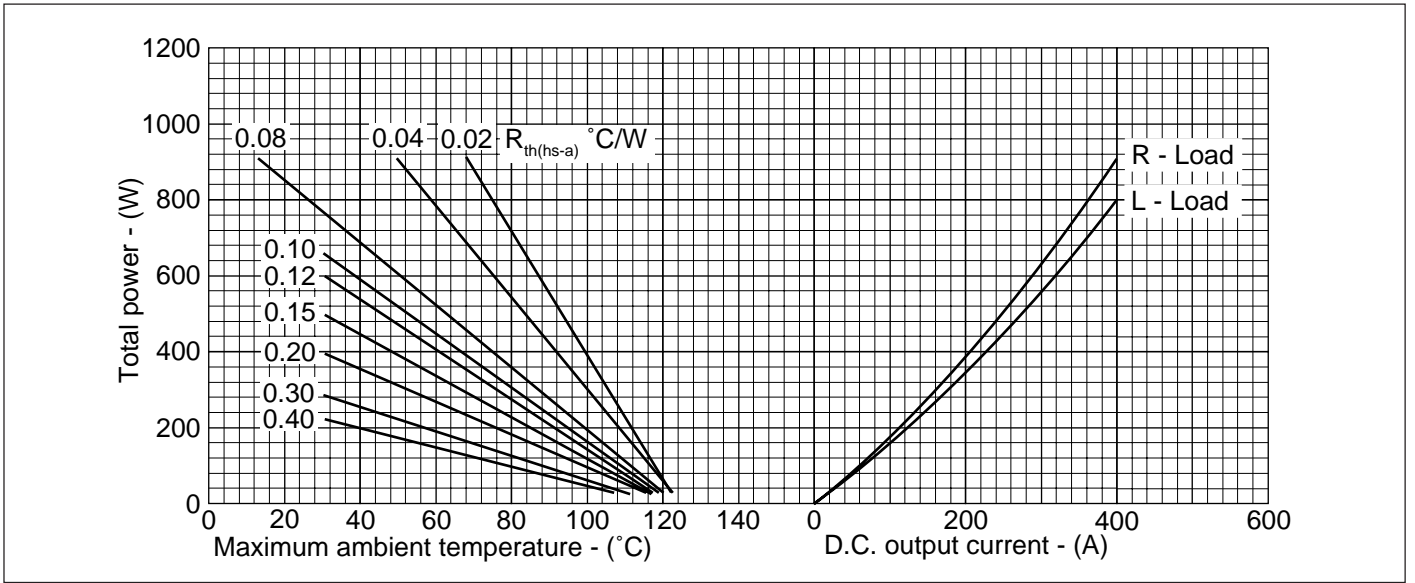


Fig. 9 50/60Hz single phase bridge dc output current vs power loss and maximum permissible ambient temperature for various values of heatsink thermal resistance.

(Note: $R_{th(hs-a)}$ values given above are true heatsink thermal resistances to ambient and already account for $R_{th(c-hs)}$ module contact thermal).

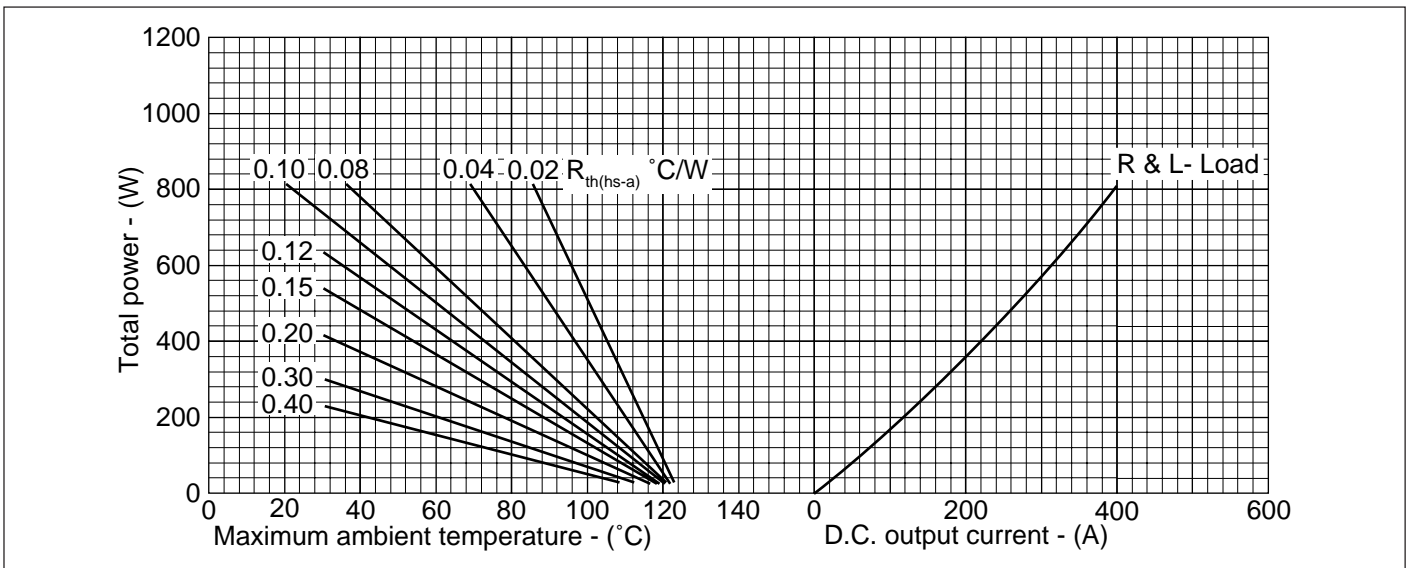
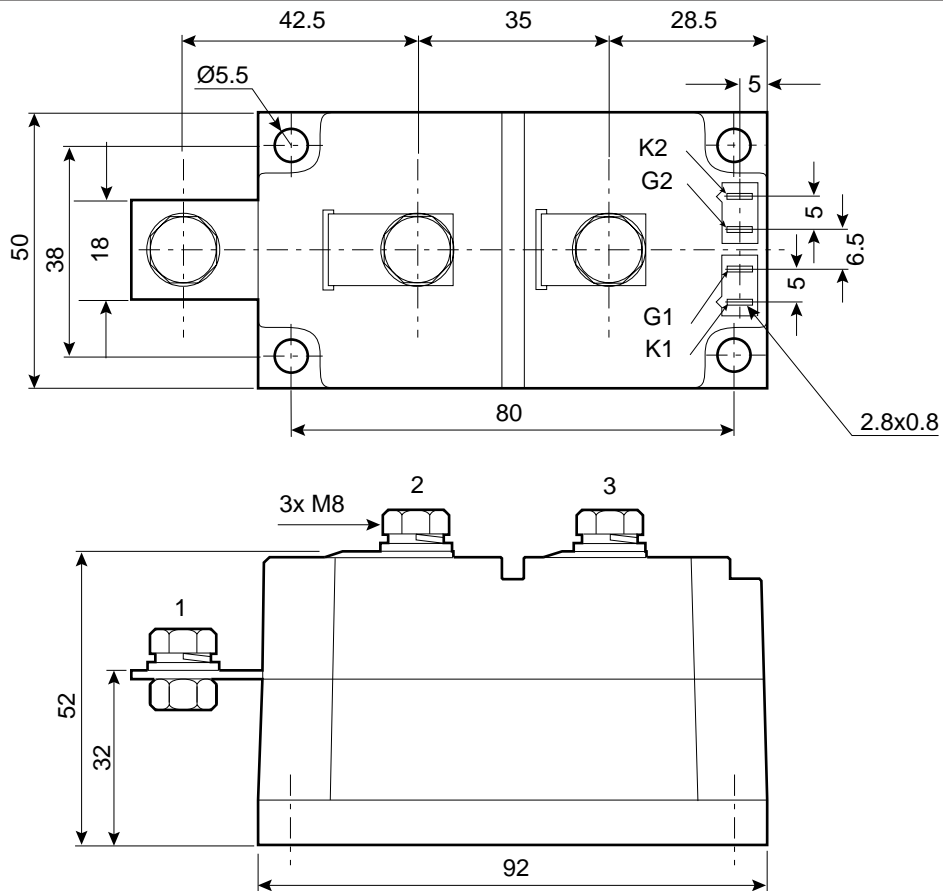


Fig. 9 50/60Hz 3- phase bridge dc output current vs power loss and maximum permissible ambient temperature for various values of heatsink thermal resistance.

(Note: $R_{th(hs-a)}$ values given above are true heatsink thermal resistances to ambient and already account for $R_{th(c-hs)}$ module contact thermal).

PACKAGE DETAILS

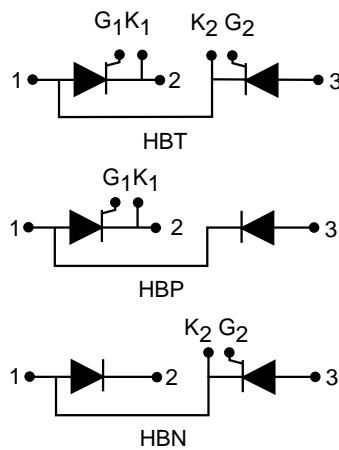
For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



Recommended fixings for mounting: M5 socket head cap screws.
 Recommended mounting torque: 5Nm (44lb.ins)
 Recommended torque for electrical connections: 8Nm (70lb.ins)
 Maximum torque for electrical connections: 9Nm (80lb.ins)
 Nominal weight: 950g

Module outline type code: MP03

CIRCUIT CONFIGURATIONS



MP03 XXX 300 Series



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